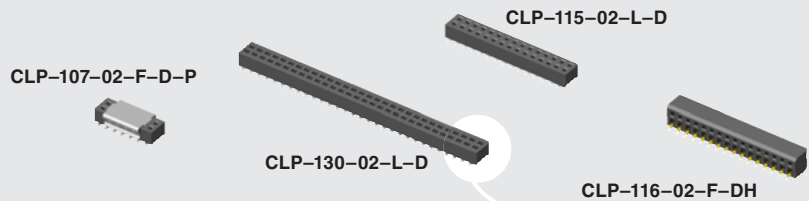




(1,27 mm) .050"



CLP SERIES

LOW PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Sn or Au over

50µ" (1,27 µm) Ni

Current Rating (CLP/FTSH):

3.3 A per pin

(1 pin powered per row)

Voltage Rating:

240 VAC/340 VDC

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

10 mΩ

Insertion Depth:

Top Entry = (1,40 mm) .055"

minimum, Bottom Entry =

(2,41 mm) .095" minimum

plus board thickness

DH Entry = (2,31 mm) .091"

to (2,67 mm) .105"

Insertion Force:

(Single contact only)

3.8 oz (1,05 N) average

Normal Force:

60 grams (0,59 N) average

Withdrawal Force:

(Single contact only)

2 oz (0,56 N) average

Max Cycles:

100 with 10µ" (0,25 µm) Au

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

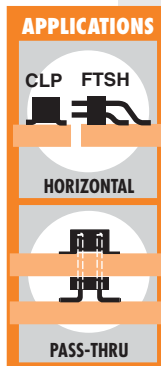
Yes

SMT Lead Coplanarity:

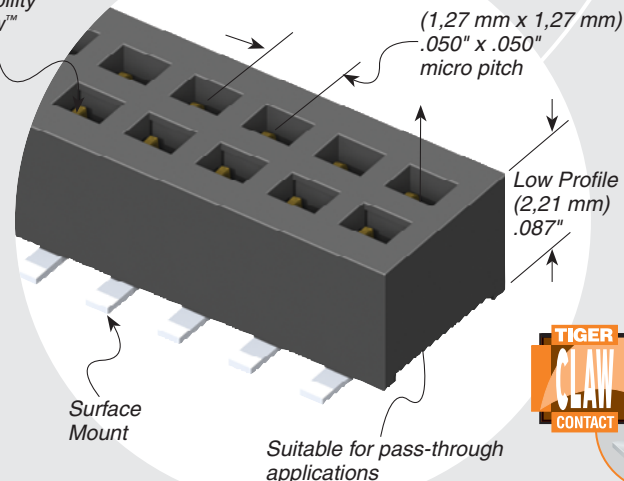
(0,10 mm) .004" max (02-35)

(0,15 mm) .006" max (36-50)

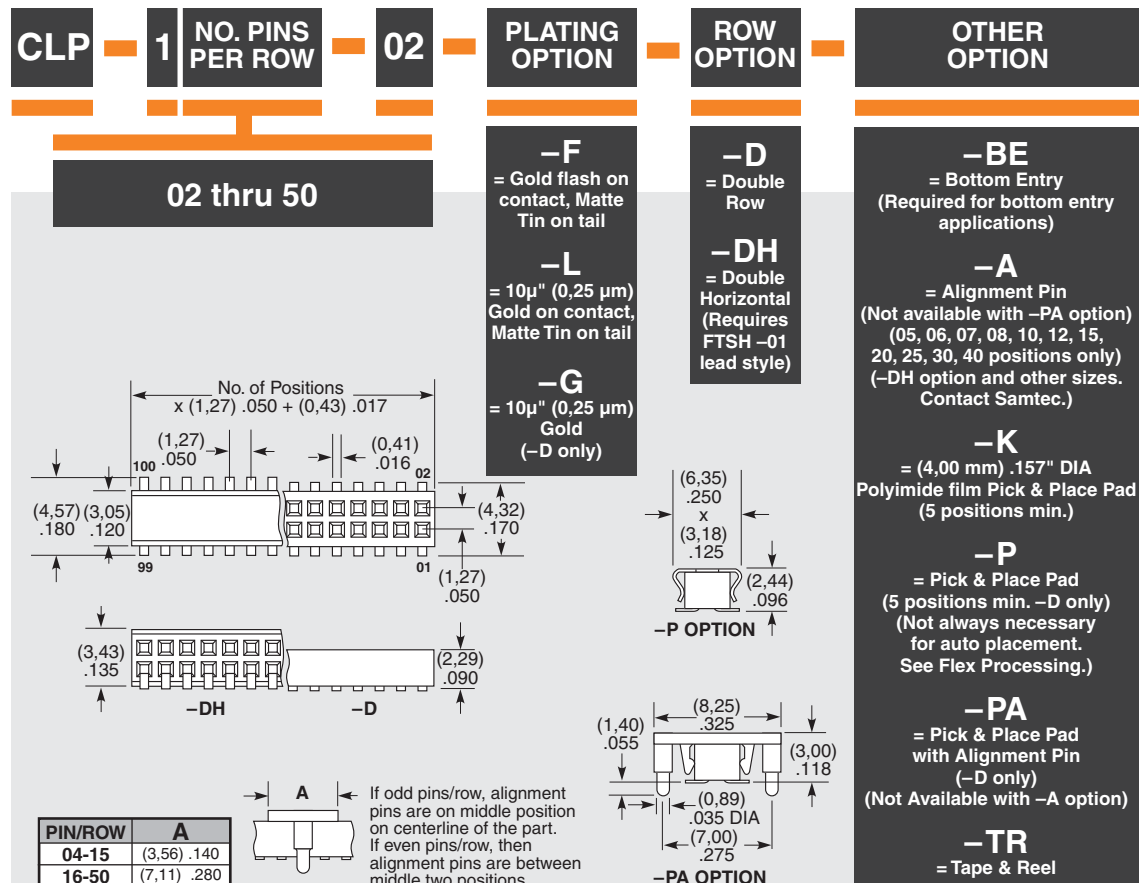
Mates with:
FTSH, FTS, FW



High reliability
Tiger Claw™
contacts



Suitable for pass-through
applications



RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Single row
 - Other platings
- Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.